

Si Technology

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2010 ~ 2011

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Advanced Process Development

- Photo lithography(including EUV, e-beam, OPC/RET), Photo Resist, Oxidation, Cleaning & CMP, Diffusion, Thin Film, CVD, Ion Implantation, Metallization, Metrology & Inspection, etc.

OPC : Optical Proximity Correction (Comput. Litho)

Module Development

- Device Isolation, Transistor, Capacitor, Dielectric
- High-K Metal Gate, SD2/SDN Gate Dielectric
- Low-K, Interconnect, etc.

FEOL/BEOL Process Integration (DRAM/Flash/Logic, etc.)

New Memory: PRAM, STT-MRAM, ReRAM, etc.

TCAD/ECAD

- Process & Device Modeling, Material Modeling
- Circuit Compact/Reliability Modeling
- Circuit Simulator Development

Advanced CMOS Image Sensor(CIS) Development

- Pixel Design, Image Signal Processing, Mixed IC Design, Analog/Desig Design
- CIS Process Development

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